

CLAIMS

1. A method of making a chip resistor comprising the steps of:
preparing an aggregate board which includes a first region
5 and a second region which are spaced from each other via an
excess portion;

forming a conductor pattern extending to bridge the first
region and the second region;

forming a resistor element in each of the first region and
10 the second region for connection to the conductor pattern; and
cutting the aggregate board at the excess portion;

the conductor pattern including a thinner-walled portion
extending across the excess portion and a thicker-walled
portion connected to the thinner-walled portion and spaced from
15 the excess portion.

2. The method according to claim 1, wherein the thinner-walled
portion has a thickness of 0.1-3.0 μ m.

20 3. The method according to claim 1, wherein the thicker-walled
portion has a thickness of 5-25 μ m.

4. The method according to claim 1, wherein the conductor
pattern forming step includes a sub-step of applying a
25 conductor paste for the thicker-walled portion and a sub-step
of applying a conductor paste for the thinner-walled portion.

5. The method according to claim 4, wherein the conductor paste for the thicker-walled portion and the conductor paste for the thinner-walled portion are baked simultaneously.

6. The method according to claim 4, wherein the conductor paste for the thicker-walled portion and the conductor paste for the thinner-walled portion are made of a same material.

7. The method according to claim 1, further comprising the step of forming a resistance adjusting groove in the resistor element.

8. A chip resistor comprising:

an insulating substrate having an upper surface and a side surface;

a first conductor pattern formed on the upper surface; and
a resistor element connected to the first conductor pattern;

the first conductor pattern including a thinner-walled portion contacting the upper surface, and a thicker-walled portion connected to the thinner-walled portion and contacting the upper surface, the thinner-walled portion being spaced from the resistor element and extending up to the side surface, the thicker-walled portion contacting the resistor element and being spaced from the side surface.

9. The resistor according to claim 8, further comprising a second conductor pattern extending on the first conductor pattern, the second conductor pattern contacting both of the thinner-walled portion and the thicker-walled portion.

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10. The resistor according to claim 8, wherein the thinner-walled portion has a thickness of 0.1-3.0 μ m, whereas the thicker-walled portion has a thickness of 5-25 μ m.

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